Reduce Cost:

In texturization pre-cleaning, SunFonergy's SPR-363 reduces KOH and H₂O₂ usage by 67%

ltem		Initial Do	sing(L)	Subsequent Dosing(L)			
петт	KOH	H ₂ O ₂	SPR-363	KOH	H_2O_2	SPR-363	
Baseline	4	12	/	0.12	1.2	/	
SunFonergy	2	6	1.4	0.04	0.4	0.028	
Consumption Reduction	50%	50%		67%	67%		

Increase Efficiency:

+0.04% eff compared to baseline

	Item	Eta	Uoc	Isc	Rs	Rsh	FF	lrev2
	Baseline	22.64%	0.6863	11.254	0.00241	2244.7	80.35	0.021
	SunFonergy	22.68%	0.6868	11.275	0.00244	1544.56	80.28	0.030





Reduce cost;

Without compromising texturization, SPR-363 significantly reduces KOH and H₂O₂ usage, decreasing overall production cost.



Increase cell efficiency;

SPR-363 can more effectively eliminate residues on wafer surfaces, thereby increasing cell efficiency.



Environmentally friendly;

Low COD, reduces after-treatment waste disposal costs.